

V. REMARKS

Entry of the Amendment is proper under 37 C.F.R. §1.116 because the Amendment: a) places the application in condition for allowance for the reasons discussed herein; b) does not raise any new issue requiring further search and/or consideration because the Amendment amplifies issues previously discussed throughout prosecution; c) does not present any additional claims without canceling a corresponding number of finally rejected claims; and d) places the application in better form for appeal, should an Appeal be necessary. The Amendment is necessary and was not earlier presented because it is made in response to arguments raised in the final rejection. The amendments to the subject claims do not incorporate any new subject matter into the claims. Thus, entry of the Amendment is respectfully requested.

Claim 1 is rejected under 35 U.S.C. 102(b) as anticipated by Hodges (U.S. Patent No. 5,590,787). The rejection is respectfully traversed.

Hodges teaches a UV light sensitive die-pac structure for securing semiconductor dies. The structure protects semiconductor integrated microcircuit dice during shipping. The structure secures the position of the die atop an ultra-violet (UV) light penetratable plate using a UV light sensitive adhesive layer. Once the structure reaches its destination, prior to removal of the die, the adhesive layer is exposed to ultraviolet light. This exposure reduces the adhesiveness or coefficient of friction of the layer, thereby facilitating die removal from the structure.

Claim 1, as amended, is directed to an ultraviolet irradiating method for emitting ultraviolet light toward a work piece and a frame holding the work piece through an ultraviolet sensitive adhesive tape applied to a back surface of the work piece. Claim 1 recites that the method includes the following steps:

a step of placing a regulating member separate from the adhesive tape applied to the back surface of the work piece, with a predetermined gap downward from a back surface of the adhesive tape prior to emitting

ultraviolet light;

a step of emitting ultraviolet light to the work piece ; and

a step of stopping, with the regulating member, the adhesive tape and the work piece closing the gap formed between the back surface of the adhesive tape and the regulating member and falling as a result of the adhesive tape softening and slackening under influence of heat, and the adhesive tape and the work piece falling together under weight of the work piece, in the step of emitting ultraviolet light.

It is respectfully submitted that the rejection is improper because the applied art fails to teach each element of claim 1 as amended. Specifically, it is respectfully submitted that the applied art fails to teach the first feature of the positional relationship between the regulating member and the adhesive tape holding the work piece before ultraviolet emission. Furthermore, it is respectfully submitted that the applied art also fails to teach the second feature of the positional relationship between the regulating member and the adhesive tape holding the work piece and softening and slackening by ultraviolet emission.

Specifically, the first feature is that the regulating member is separate from the adhesive tape applied to the back surface of the work piece, and is placed with a predetermined gap downward from a back surface of the adhesive tape prior to emitting ultraviolet light. The second feature is that the regulating member stops the adhesive tape and the work piece closing the gap formed between the back surface of the adhesive tape and the regulating member and falling as a result of the adhesive tape softening and slackening under influence of heat, and the adhesive tape and the work piece falling together under weight of the work piece, in the step of emitting ultraviolet light.

As a result, at least for the reasons set forth above, it is respectfully submitted that claim 1 is allowable over the applied art.

Withdrawal of the rejection is respectfully requested.

Claims 2-6, 9, 12, 13 and 15 are rejected under 35 U.S.C. 103(a) as unpatentable over Hodges in view of Farnworth et al. (U.S. Patent No. 6,202,292). The rejection is respectfully traversed.

Farnworth discloses a system for releasing at least a portion of a carrier film from at least one selected semiconductor die and includes a base, a vacuum source and a die pick up mechanism. The base includes a plate member configured to be moved laterally within a periphery of a frame supporting the carrier film having a semiconductor wafer adhered thereto. The plate member includes a plurality of supports disposed within the periphery, positioned below the carrier film and sufficiently mutually laterally spaced to permit deflection of portions of the carrier film therebetween responsive to a pressure differential across the carrier film. The vacuum source is operatively connected with the base to create a vacuum between the plurality of supports. The die pick up mechanism is laterally positioned proximate to the plate member in a plurality of locations on an opposite side of the carrier film from the plurality of supports.

Claim 4, as amended, is directed to an ultraviolet irradiating apparatus for emitting ultraviolet light toward a work piece and a ring-shaped frame holding the work piece through an ultraviolet sensitive adhesive tape applied to a back surface of the work piece. Claim 4 recites that the apparatus includes regulating means disposed at a predetermined distance from a back surface of the adhesive tape, prior to emitting ultraviolet light, for stopping the adhesive tape and the work piece closing the gap formed between the back surface of the adhesive tape and the regulating member and falling as a result of the adhesive tape softening and slackening under influence of heat, and the adhesive tape and the work piece falling together under weight of the work piece, during an ultraviolet light emission toward the work.

It is respectfully submitted that none of the applied art, alone or in combination, teaches or suggests the features of claim 4 as amended. Specifically, it is respectfully submitted that none of the applied art, alone or in combination, teaches or suggests the first and second features discussed above. Thus, it is respectfully submitted that one of ordinary skill in the art would not be motivated to combine the features of the applied art because such combination would not result in the claimed invention. As a result, it is

respectfully submitted that claim 4 is allowable over the applied art.

Claims 2 and 3 depend from claim 1 and include all of the features of claim 1. Claims 6, 9, 12, 13 and 15 depend from claim 4 and include all of the features of claim 4. Thus, it is respectfully submitted that the dependent claims are allowable at least for the reason the independent claims are allowable as well as for the features they recite.

Withdrawal of the rejection is respectfully requested.

Claims 7, 8 and 10-12 are rejected under 35 U.S.C. 103(a) as unpatentable over Hodges in view of Farnworth and further in view of Summersgill et al. (U.S. Patent No. 6,348,999). The rejection is respectfully traversed.

Summersgill discloses a micro relief element which includes a first layer of a first substrate, an overlay and at least one relief feature. The first layer has a receptive surface capable of retaining a relief forming polymer. The overlay has a desired thickness of the relief forming polymer over the receptive surface. The at least one relief feature is formed from the relief forming polymer and which protrudes above the overlay.

Claims 7, 8 and 10-12 depend from claim 4 and include all of the features of claim 4. Thus, it is respectfully submitted that the dependent claims are allowable at least for the reason claim 4 is allowable as well as for the features they recite.

Withdrawal of the rejection is respectfully requested.

Claim 14 is rejected under 35 U.S.C. 103(a) as unpatentable over Hodges in view of Farnworth and further in view of Okamoto et al. (U.S. Patent No. 6,153,357). The rejection is respectfully traversed.

Okamoto teaches a process for fabricating semiconductor integrated circuit devices.

Claim 14 depends from claim 4 and includes all of the features of claim 4. Thus, it is respectfully submitted that claim 14 is allowable at least for the reason claim 4 is allowable as well as for the features it recites.

Withdrawal of the rejection is respectfully requested.

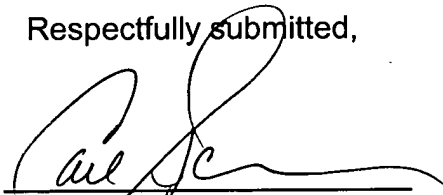
In view of the foregoing, reconsideration of the application and allowance of the pending claims are respectfully requested. Should the Examiner believe anything further is desirable in order to place the application in even better condition for allowance, the Examiner is invited to contact Applicants' representative at the telephone number listed below.

Should additional fees be necessary in connection with the filing of this paper or if a Petition for Extension of Time is required for timely acceptance of the same, the Commissioner is hereby authorized to charge Deposit Account No. 18-0013 for any such fees and Applicant(s) hereby petition for such extension of time.

Respectfully submitted,

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Enclosure(s): Amendment Transmittal

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